



APPLICATIONS

- Battery-Powered Devices
- High-Efficiency SMPS
- Embedded Computing
- Input Filters

FEATURES

- Size 4mmx4mmx3mm
- Semi-Shielded Construction
- Low DCR
- Low Stray Field
- Max Operating Temp +125°C
- RoHS/REACH-Compliant, Halogen-Free

ELECTRICAL CHARACTERISTICS

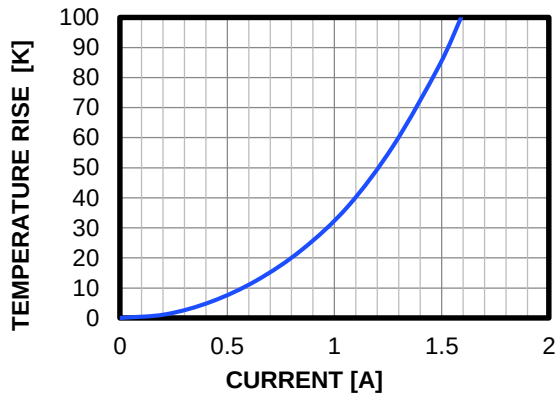
Parameter			Value	Unit
Inductance ⁽¹⁾	L	±20%	33	μH
Resistance	R_{DC}	Typ	330	mΩ
Resistance _{MAX}	$R_{DC\ MAX}$	Max	400	mΩ
Rated Current ⁽²⁾	I_R	Typ	1.1	A
Saturation Current _{25°C} ⁽³⁾	$I_{SAT\ 25°C}$	Typ	1.2	A
Saturation Current _{100°C} ⁽⁴⁾	$I_{SAT\ 100°C}$	Typ	0.97	A
Resonance Frequency	f_r	Typ	16	MHz

GENERAL SPECIFICATIONS

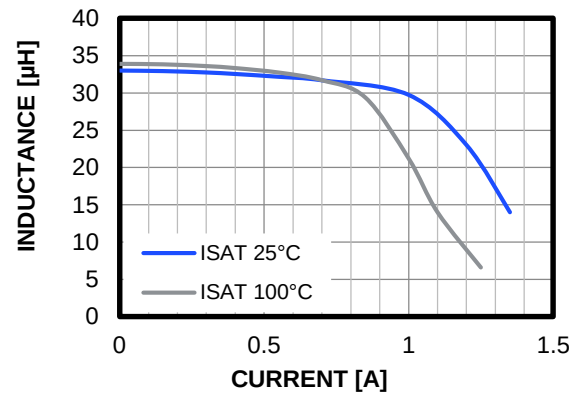
⁽¹⁾ Inductance	Measured at 100kHz, 100mA
⁽²⁾ Rated Current	Rated current will cause the coil temperature rise ΔT of 40K <i>I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35μm Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.</i>
⁽³⁾ Saturation Current _{25°C}	Saturation current will cause L to drop from 30% at 25°C ambient temperature
⁽⁴⁾ Saturation Current _{100°C}	Saturation current will cause L to drop from 30% at 100°C ambient temperature
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently
Operating Condition	Operating temperature: -40°C to +125°C (including temp rise) Should not exceed +125°C under worst-case operation conditions
Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH

TYPICAL PERFORMANCE CURVES

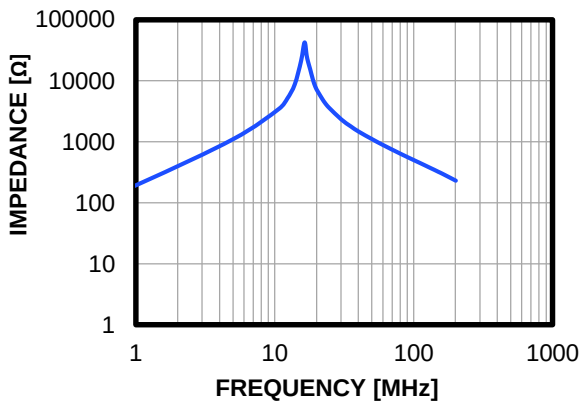
Temperature Rise vs. Current



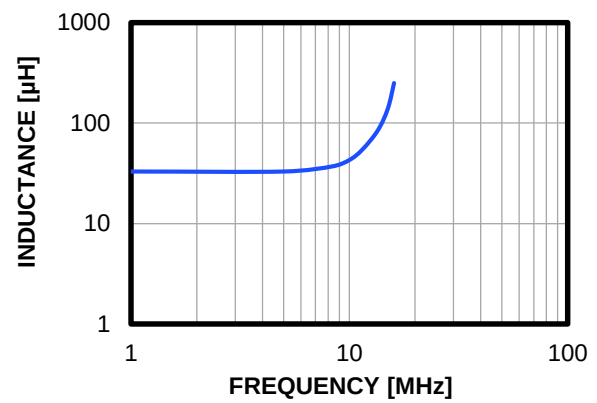
Inductance vs. Current



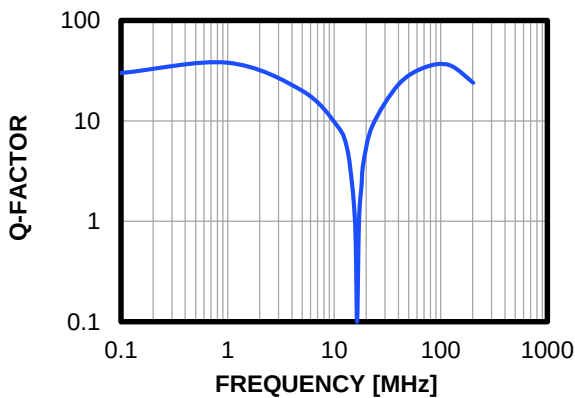
Impedance vs. Frequency



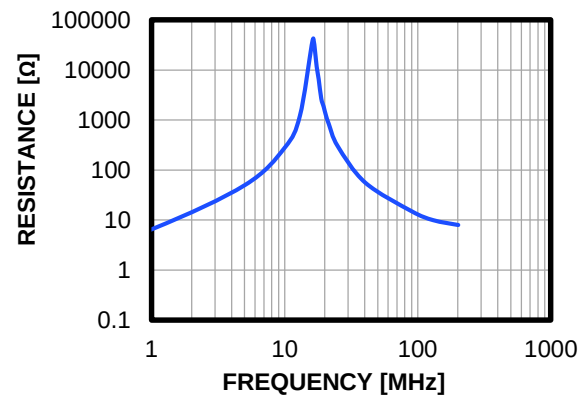
Inductance vs. Frequency



Quality Factor vs. Frequency



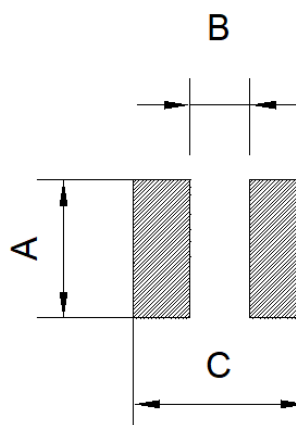
AC Resistance vs. Frequency



LAND PATTERN

Dimensions

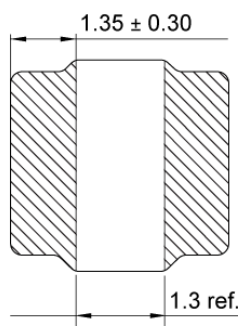
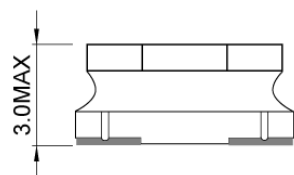
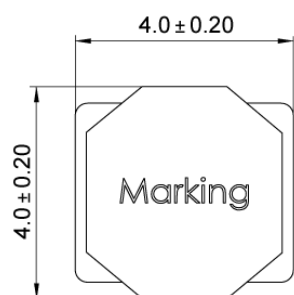
A	4.50 ref.
B	1.50 ref.
C	4.50 ref. (units in mm)



PRODUCT PACKAGE AND DIMENSIONS

Dimensions

(units in mm)



TOP MARKING

Marking

Inductance Code	330
-----------------	-----

ORDERING INFORMATION

Part Number	L ⁽¹⁾	R_{DC}	I_R ⁽²⁾	$I_{SAT\ 25^{\circ}C}$ ⁽³⁾	$I_{SAT\ 100^{\circ}C}$ ⁽⁴⁾
	$\pm 20\%$ (μ H)	Typ ($m\Omega$)	Typ (A)	Typ (A)	Typ (A)
MPL-SE4030-R68	0.68	10	6	7.5	6.5
MPL-SE4030-1R0	1	14	5.5	7	5.7
MPL-SE4030-2R2	2.2	30	3.7	5.5	4.2
MPL-SE4030-3R3	3.3	40	3.3	4.1	3.6
MPL-SE4030-4R7	4.7	62	2.6	3.4	2.7
MPL-SE4030-6R8	6.8	90	2.2	2.9	2.2
MPL-SE4030-100	10	100	2	2.2	1.75
MPL-SE4030-150	15	185	1.4	1.8	1.47
MPL-SE4030-220	22	220	1.3	1.5	1.12
MPL-SE4030-330	33	330	1.1	1.2	0.97
MPL-SE4030-470	47	480	0.9	1	0.82

GENERAL SPECIFICATIONS

⁽¹⁾ Inductance	Measured at 100kHz, 100mA
⁽²⁾ Rated Current	Rated current will cause the coil temperature rise ΔT of 40K <i>I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35μm Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.</i>
⁽³⁾ Saturation Current $_{25^{\circ}C}$	Saturation current will cause L to drop from 30% at 25 $^{\circ}C$ ambient temperature
⁽⁴⁾ Saturation Current $_{100^{\circ}C}$	Saturation current will cause L to drop from 30% at 100 $^{\circ}C$ ambient temperature
Temperature Test Condition	Electrical specifications measured at 25 $^{\circ}C$, 35% RH if not given differently
Operating Condition	Operating temperature: -40 $^{\circ}C$ to +125 $^{\circ}C$ (including temp rise) Should not exceed +125 $^{\circ}C$ under worst-case operation conditions
Storage Condition	Tape and Reel packaging: -10 $^{\circ}C$ to +40 $^{\circ}C$ Humidity: <50% RH

REVISION HISTORY

Revision #	Revision Date	Description	Pages Updated
1.0	9/19/2022	Initial Release	-

Notice: The information in this document is subject to change without notice. Please contact MPS for current specifications. Users should warrant and guarantee that third-party Intellectual Property rights are not infringed upon when integrating MPS products into any application. MPS will not assume any legal responsibility for any said applications.